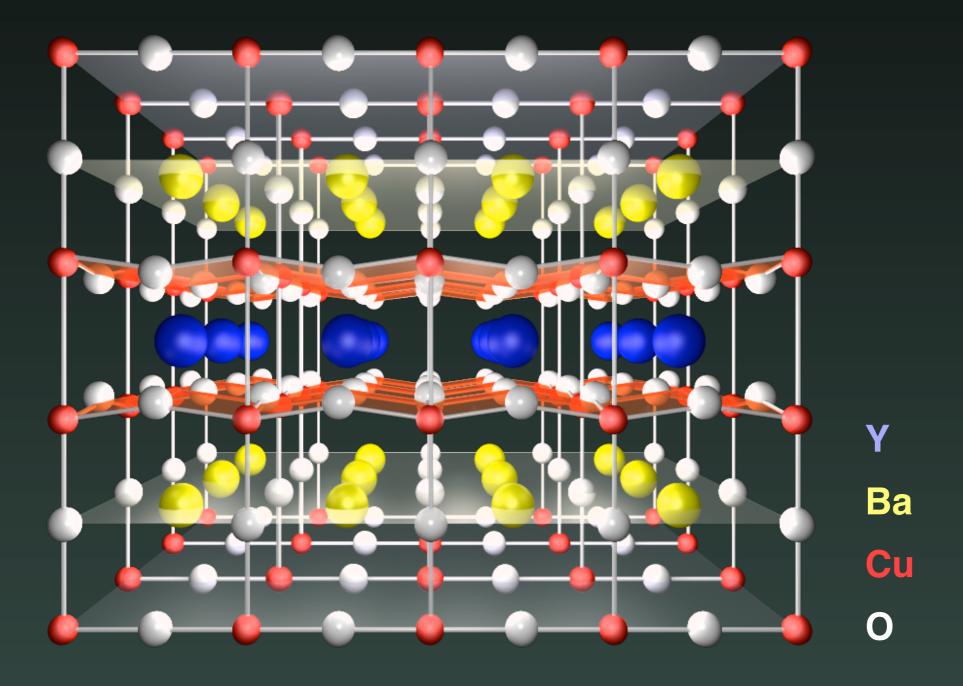


Concepts for Designing Novel Materials Using Oxide Heterostructures

Jochen Mannhart and Thilo Kopp

Center for Electronic Correlations and Magnetism
University of Augsburg



Growth of Complex Oxide Multilayers

Growth by MBE:

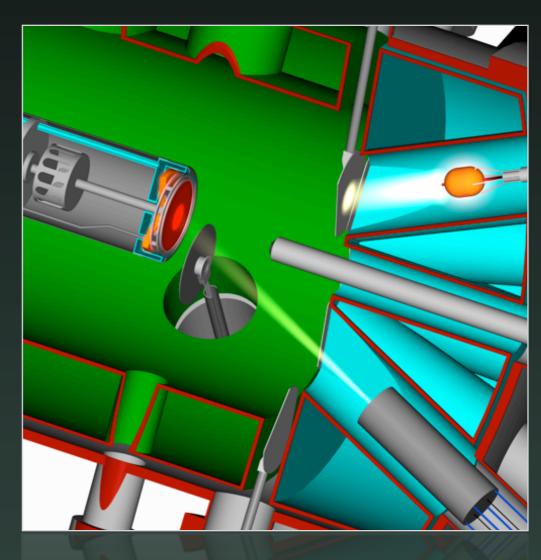
- Bozovic, Eckstein, Schlom (Varian)
- Locquet (IBM Zurich)

- ...

Keys for progress

- Activated oxygen
- Accurate rate control
- RHEED
- Substrate termination





A. Schmehl

Now, growth of complex oxide multilayers also by pulsed laser deposition

Many Good Reasons to Grow Materials on a Layer-by-Layer Basis

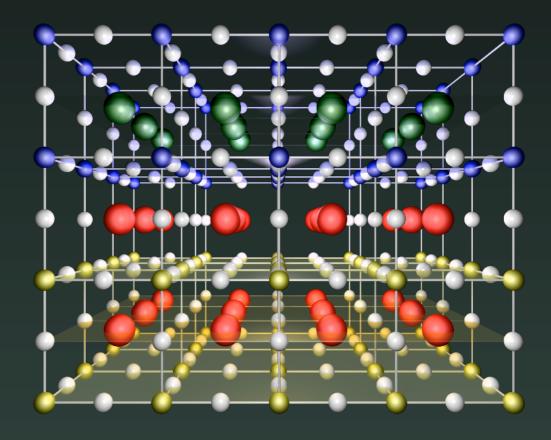
- Freedom to design, grow stacking sequences not realized by nature in the bulk (tricolor lattices)
- Grow device structures (tunnel junctions, FETs, ...)
- Create novel phases and metastable materials,
 large scale, single-crystal quality, easily measurable
- Utilize epitaxial stress and strain
- Add doping layers
- ▶ ...

Also Growth of Well Defined Interfaces Possible

seminal publications: Ohtoma & Hwang (2002, 2004)



- L. Fitting Kourkoutis,
- D. Muller (Cornell)

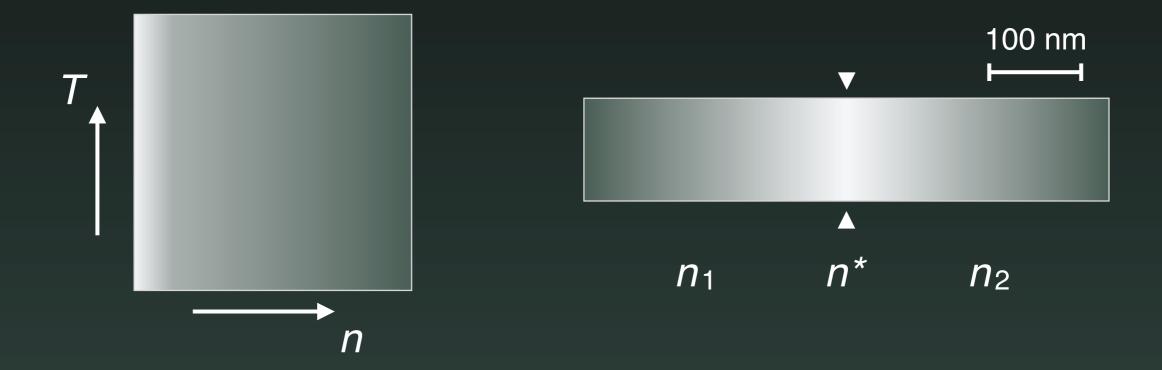


LaAlO₃ - SrTiO₃

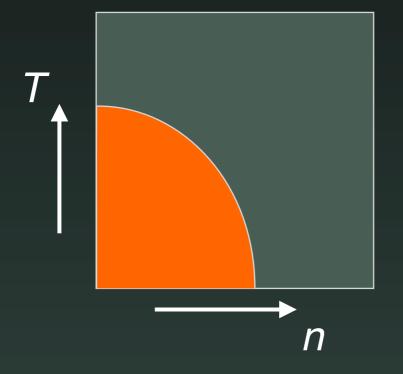
Many Good Reasons to Grow Materials on a Layer-by-Layer Basis

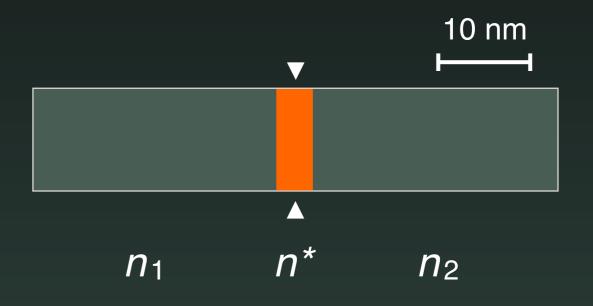
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- ▶ ...
- Create materials with novel electronic systems generated at interfaces in systems with strong electronic correlations

Standard Semiconductors - Band Bending at Interfaces

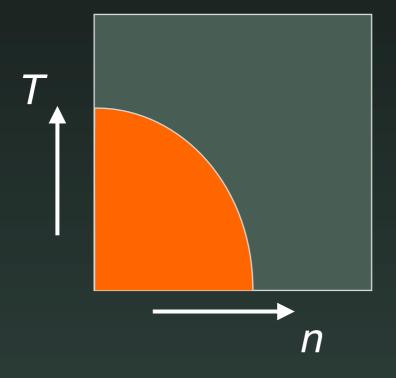


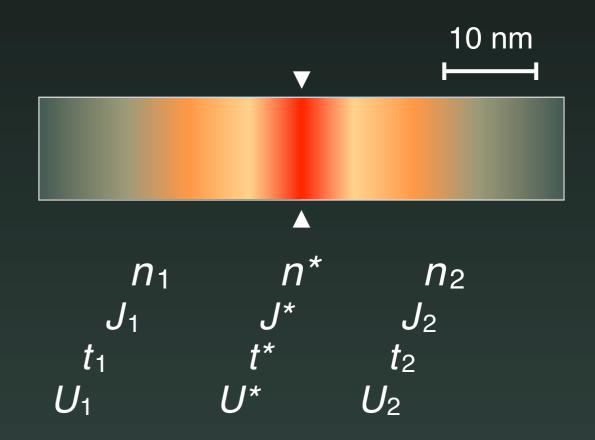
Electronic Reconstruction at Interfaces in Correlated Electronic Systems





Novel Electronic Phases at Interfaces in Correlated Electronic Systems





Plus:

- charge transfer, space charge effects, band bending ...
- possible misalignment
- orbital reconstruction
- altered:
 - Madelung energies
 - hybridization (also hybridization through interface)
 - screening, dielectric and magnetic environment
 - orbital order (including frustrated orbital order)
 - spin order (including frustrated spin order)

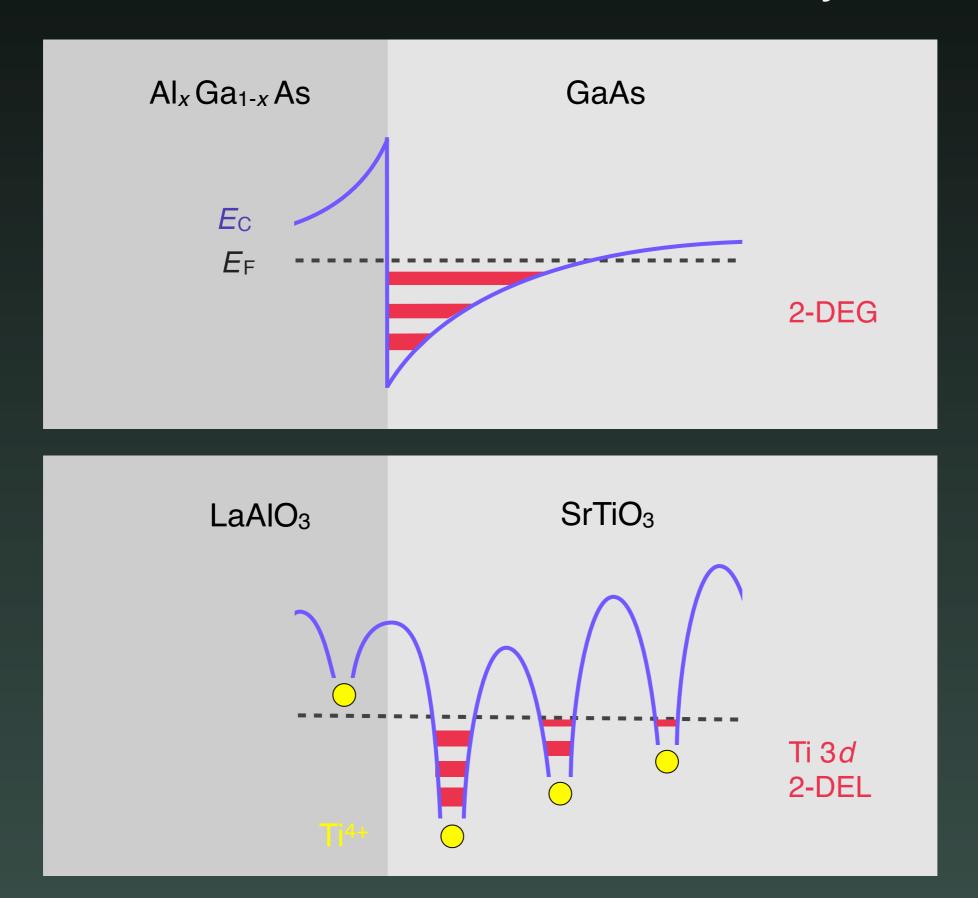
talks by Tchakhalian, Eckstein, Hwang, Abbamonte, Pentcheva, Okamoto, Bozovic, ...

Plus:

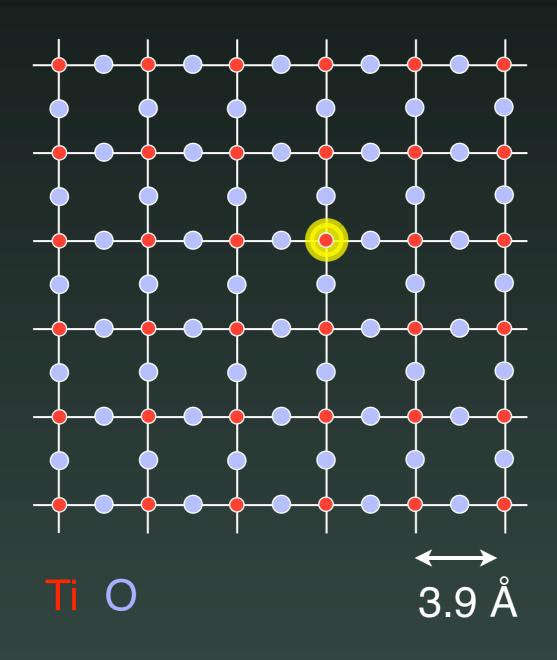
- use gradients
- multiferroic coupling generated by interface
- use reduction of dimensionality
- decouple mobile carriers from excitations (superconducting pairing!)
- non-equilibrium effects, induced for example by current injection

talks by Tchakhalian, Eckstein, Hwang, Abbamonte, Pentcheva, Okamoto, Bozovic, ...

The LaAlO₃-SrTiO₃ Interface Electronic System



The LaAlO₃-SrTiO₃ Interface Electronic System



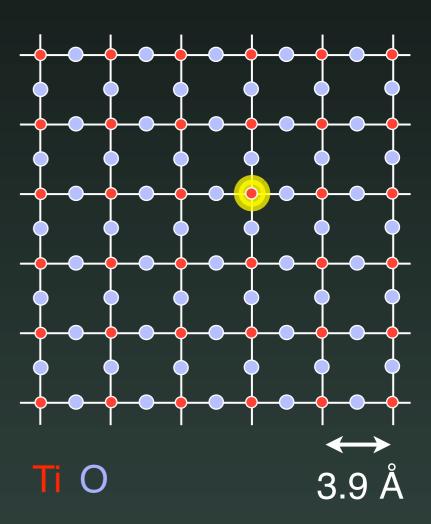
$$n \sim 5 \times 10^{12} - 5 \times 10^{14} \text{/cm}^2$$

$$r_{\rm s} = (1/\pi a_{\rm B}^2 n)^{1/2} \sim 5 - 50$$

TiO₂-plane

The Energy of the Electron System

$$E = E_{H} + E_{kin} + E_{xc} + E_{corr} + E_{ext}$$



The Energy of a Capacitor with LaAlO₃-SrTiO₃ Plates

$$E = E_{H} + \sum_{i} E_{\text{kin},i} + \sum_{i} E_{\text{xc},i} + \sum_{i} E_{\text{corr},i} + \sum_{i} E_{\text{ext},i}$$

$$E = \frac{1}{2C} Q^{2}$$

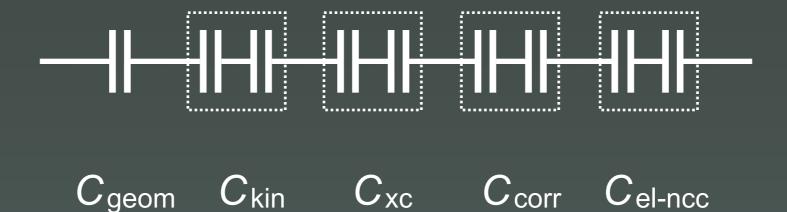
for homogenous electron systems:

$$E_{\rm H} + \sum_{i} E_{{\rm ext},i} = \frac{d}{\varepsilon_0 \varepsilon_r A} Q^2$$

neglecting tunneling and exchange contributions between the plates

The General Equation for the Capacitance of a Capacitor

$$1/C = 1/C_{\text{geom}} + \sum_{i} 1/C_{\text{kin},i} + \sum_{i} 1/C_{\text{xc},i} + \sum_{i} 1/C_{\text{corr},i} + \sum_{i} 1/C_{\text{el-ncc},i}$$



the electron systems of the electrodes have their own capacities

When is $C = C_{geom}$?

$$1/C = 1/C_{\text{geom}} + \sum_{i} 1/C_{\text{kin},i} + \sum_{i} 1/C_{\text{xc},i} + \sum_{i} 1/C_{\text{corr},i} + \sum_{i} 1/C_{\text{el-ncc},i}$$

$$\frac{d}{\varepsilon_{r}} \qquad a_{\text{B}} \qquad r_{\text{s}}a_{\text{B}} \qquad 0$$

Transition to Quantum Electronics

$$C = \varepsilon_0 \varepsilon_r \frac{A}{d}$$
 is only valid in the limit of large d/ε_r

The General Equation for the Capacitance of a Capacitor

$$1/C = 1/C_{\text{geom}} + \sum_{i} 1/C_{\text{kin},i} + \sum_{i} 1/C_{\text{xc},i} + \sum_{i} 1/C_{\text{corr},i} + \sum_{i} 1/C_{\text{el-ncc},i}$$

2D Homogenous Electron Systems:

$$\frac{C_{\text{geom}}}{A} = \frac{\varepsilon_0 \varepsilon_r}{d}$$

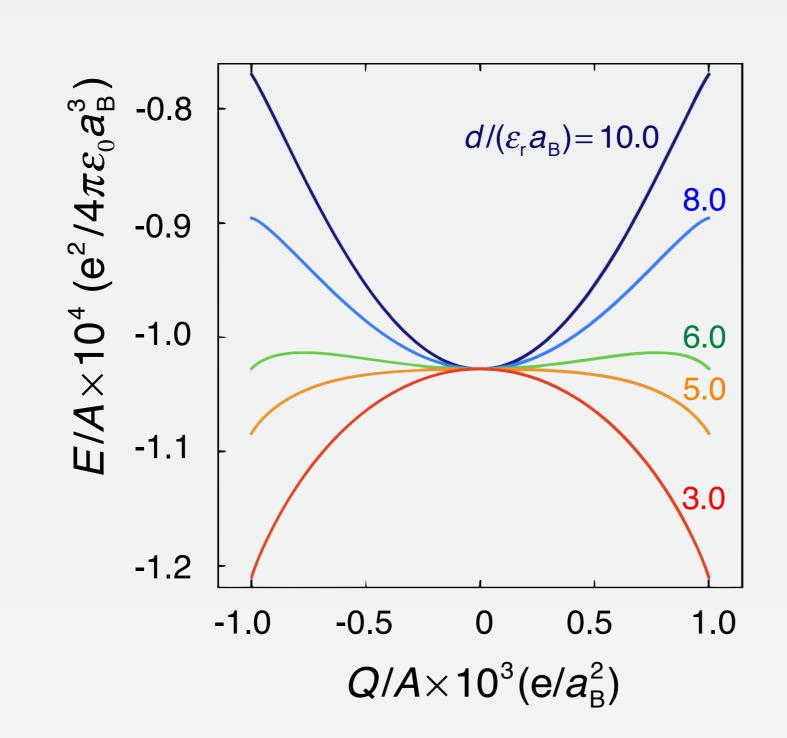
$$\frac{C_{\text{kin},i}}{A} = 4\varepsilon_0 \frac{m_i^*/m}{a_B} = e^2 \rho_i^{(2D)} (E_F)$$

$$\frac{C_{xc,i}}{A} = -2^{3/2} \frac{\varepsilon_0 \varepsilon_{eff,i}}{a_B r_s}$$

$$C_{\text{el-ncc},i} = 0$$

$$\frac{C_{\text{corr},i}}{A} = -\frac{\varepsilon_0 \varepsilon_{\text{eff},i}}{a_B} f(r_s)$$

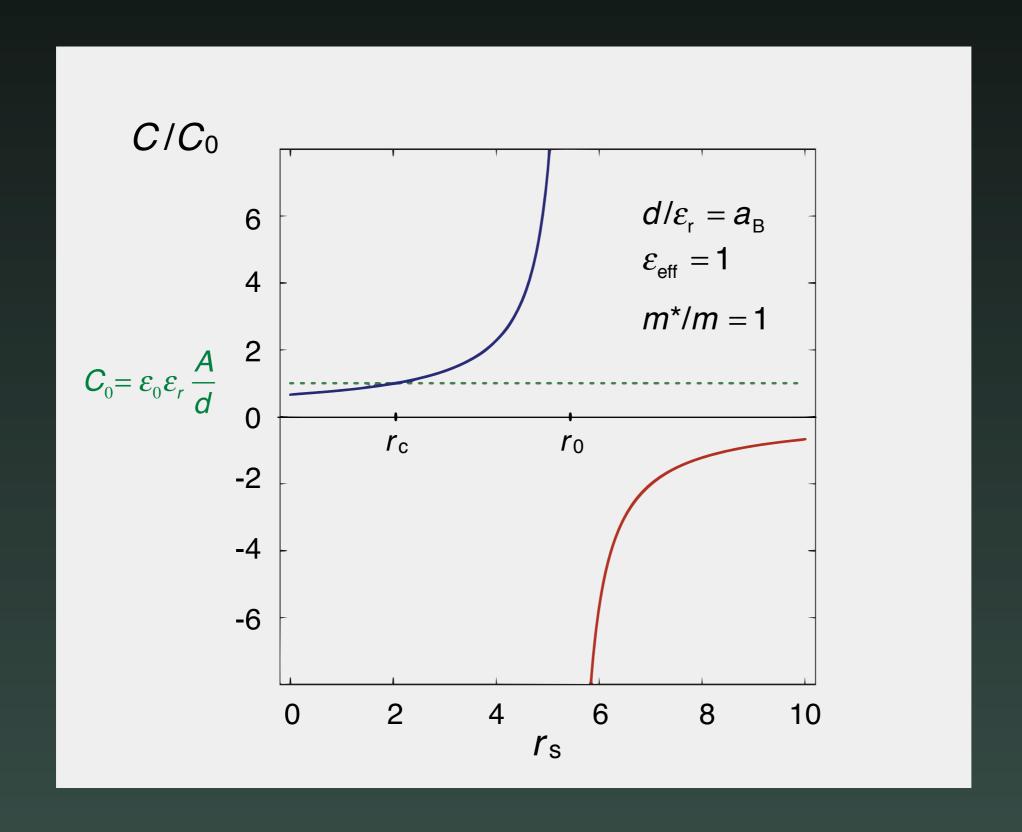
Energy of Capacitors with 2D Electron Gases in the Plates



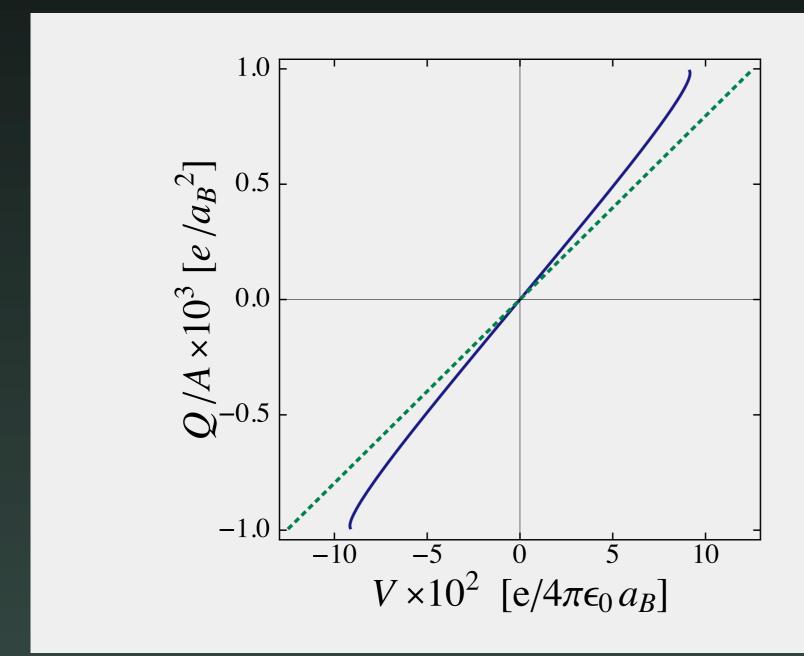
$$n = 3.6 \times 10^{13} \text{ cm}^{-2}$$

 $m^*/m = 1$
 $\varepsilon_{\text{eff}} = 1$

Capacitance of a Capacitor with 2D Electron Gases in the Plates

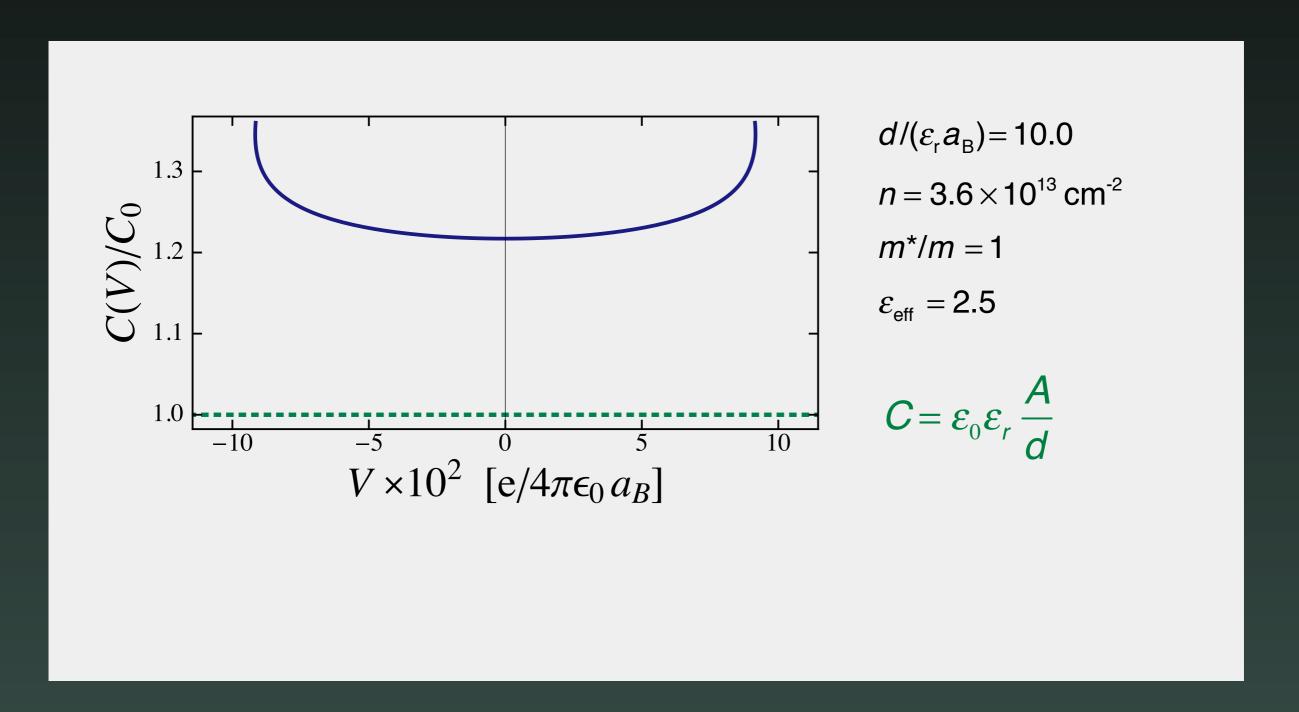


C(V)-Characteristic of a Capacitor with 2D Electron Gases in the Plates

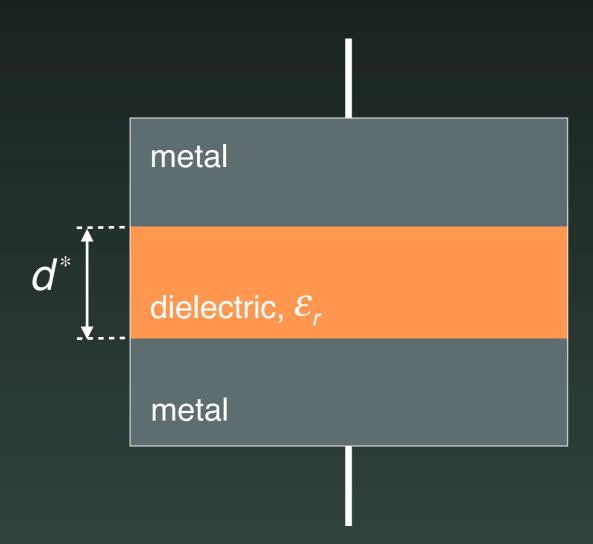


$$d/(\varepsilon_{\rm r}a_{\rm B})$$
= 10.0
 n = 3.6 × 10¹³ cm⁻²
 m^*/m = 1
 $\varepsilon_{\rm eff}$ = 2.5

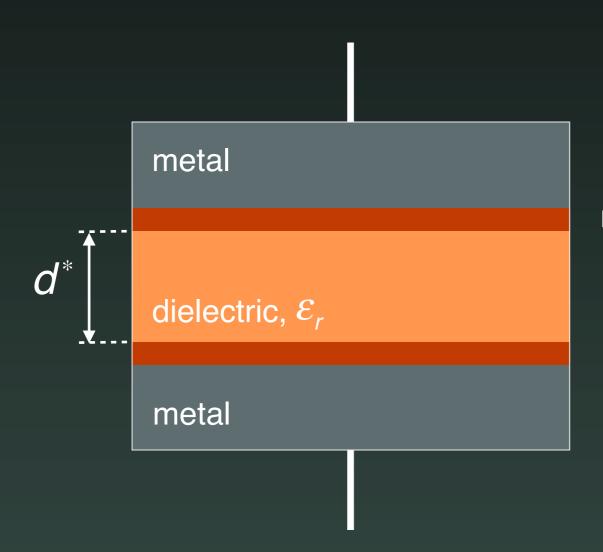
C(V)-Characteristic of a Capacitor with 2D Electron Gases in the Plates



Capacitor with $C > \varepsilon_0 \varepsilon_r \frac{A}{d^*}$



Capacitor with $C > \varepsilon_0 \varepsilon_r \frac{A}{d^*}$



metallic layer with large C

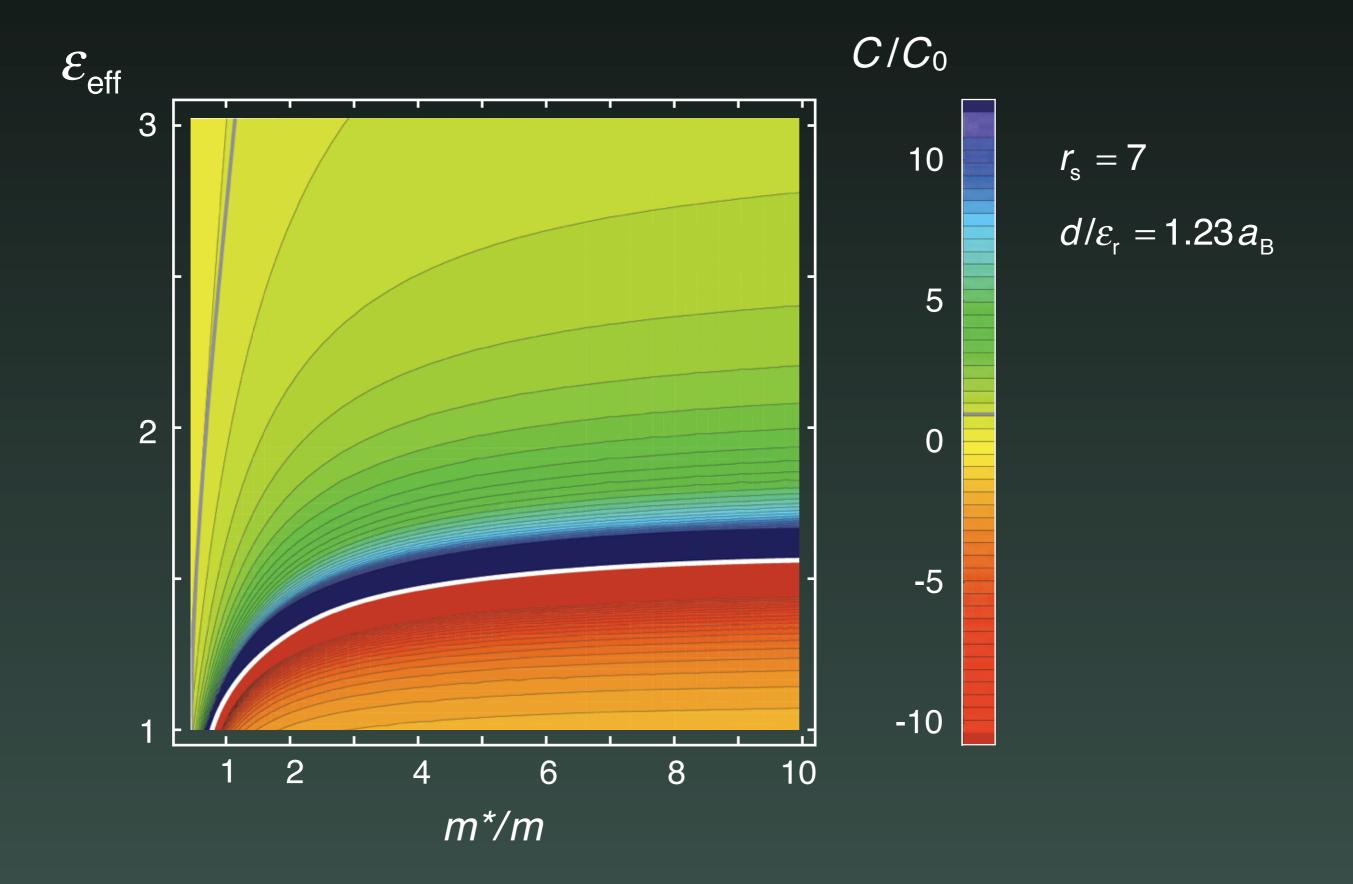
metallic layer with large C

Materials of Interest

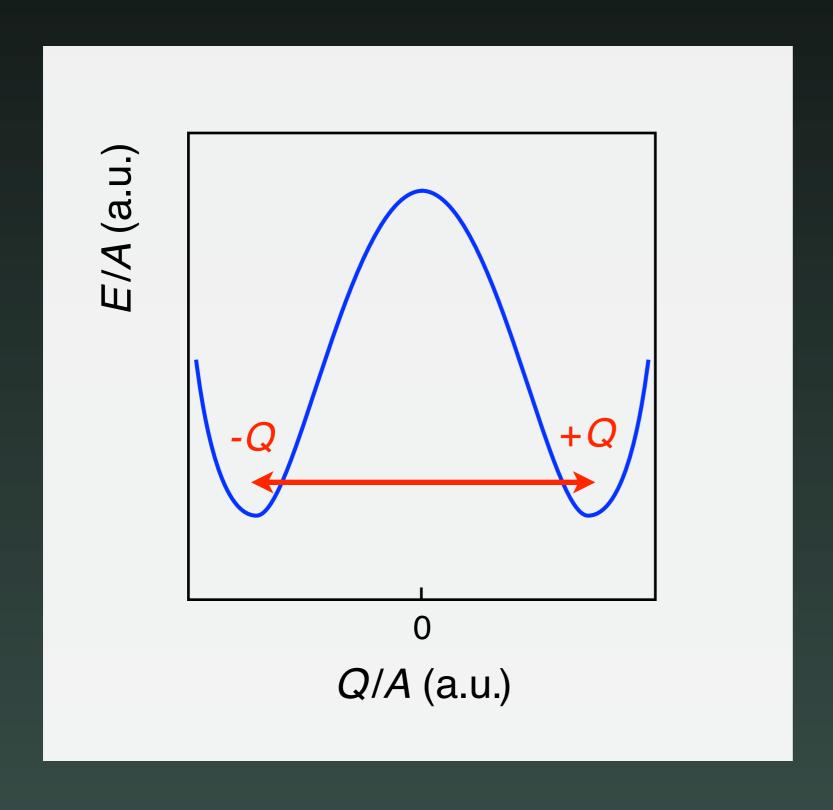
- interface electron systems, e.g., LaAlO₃-SrTiO₃, LaVO₃-SrTiO₃
- standard metals with low carrier densities
- strongly correlated systems, transition-metal oxides
- graphene, nanotubes (Latessa et al., PRB (2005): Ilani et al., Nature Physics (2006))
- \triangleright van-Hove systems (for small-C devices)

. . .

Capacitance of a Capacitor with 2D Electron Gases in the Plates



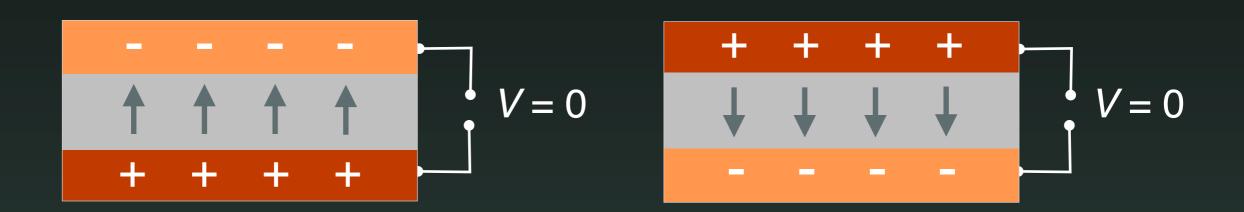
States of Capacitors with Negative C



switching between the two states with bias pulses

- memory devices?
- coherent states?

Ferroelectric-type Behavior without Ferroelectric Compound



Reminiscent of ferroelectrics, but

- no ferroelectric compounds
- no discharging, no depolarization
- electronic effect, fast

Capacitors with Electron Systems with Negative Compressibilities

- 1. negative compressibilities of the electron system cause instabilities: charge density wave, stripes, other inhomogeneous phases
- 2. coherent states of both plates? (Moon et al. (1995), Zheng et al. (1997))
- 3. charge imbalance between plates, negative *C*

controlling parameters:

- material properties (strongly correlated systems?)
- device geometry
- experimental conditions (T, V, history)

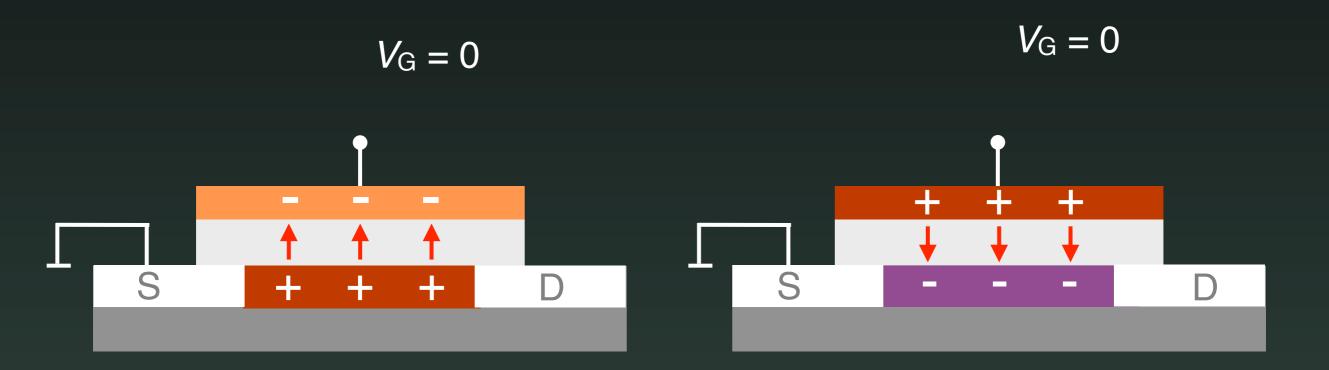
Other Work on Total Negative Capacitances

for example:

- generated by using amplifier circuits (Beavis, 1954)
- ▶ found for electron injection through interfaces (Omura, 2000)
- proposed for structures comprising ferroelectrics (Salahuddin and Datta, 2007)

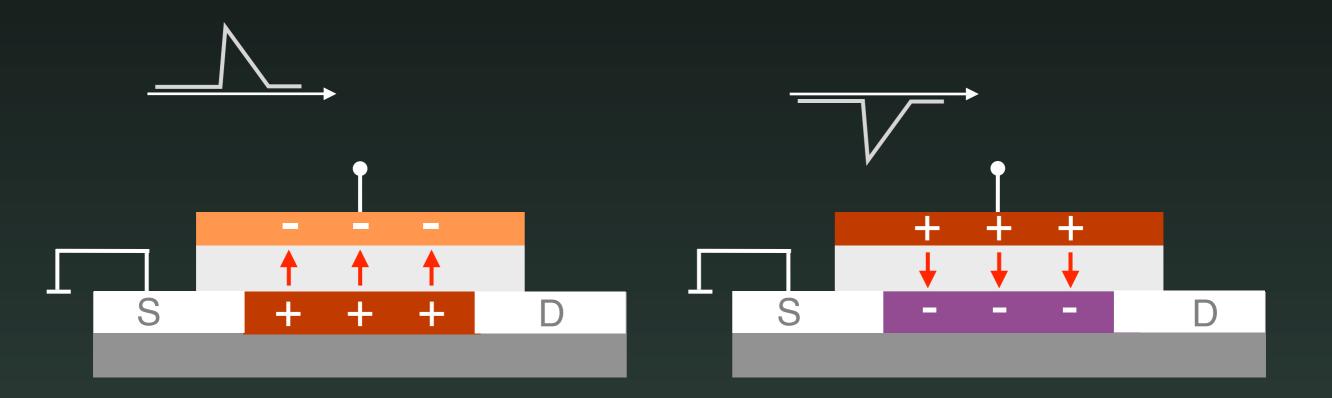
plus considerable experimental and theoretical work on negative contributions to a total positive capacitance

MOSFETs with Negative-C Gate Stacks



Information carriers: electrons with neutralized global Coulomb energies

MOSFETs with Negative-C Gate Stacks



Information carriers: electrons with neutralized global Coulomb energies

Overview on Impedances

negative capacitor

i

 $1/\omega$

standard capacitor

-i

 $1/\omega$

 $Z = -i \frac{1}{\omega C}$

phase shift

f-dependence

negative inductor

-i

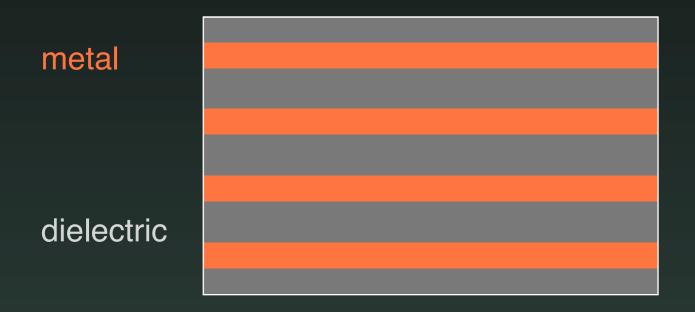
 ω

standard inductor

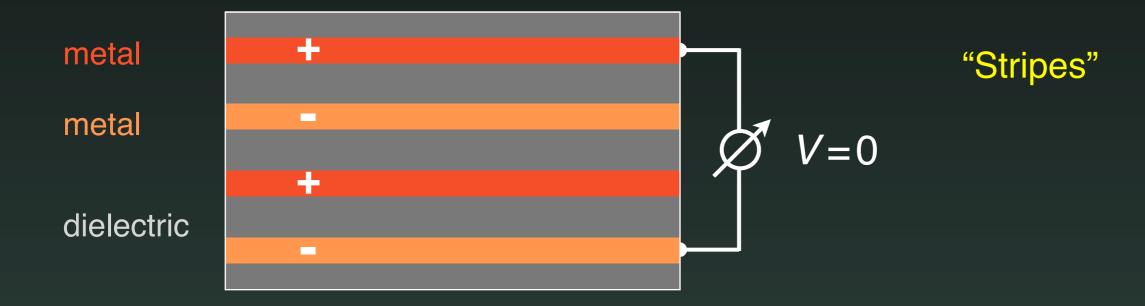
i

 ω

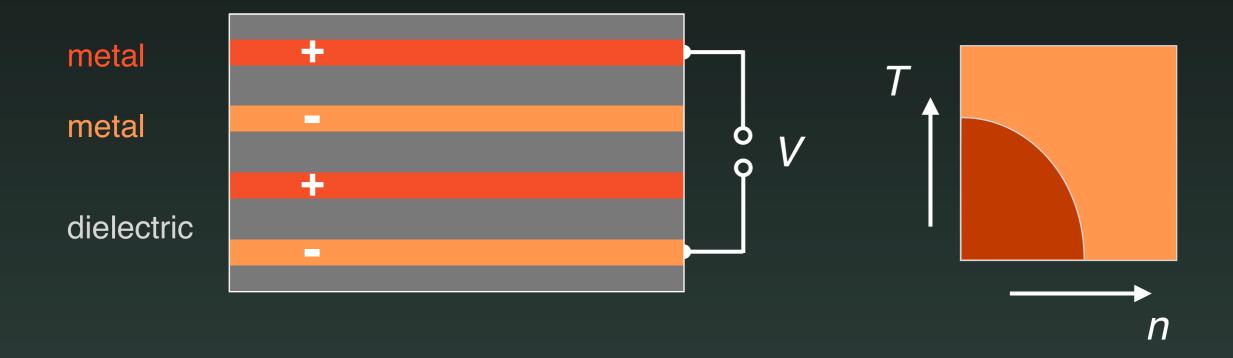
$$Z = i \omega L$$



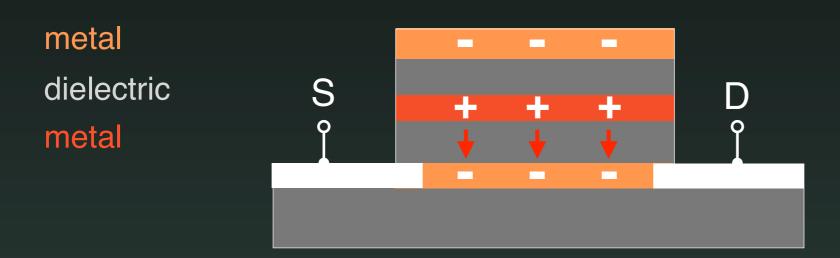
Artificial material with negative effective $\varepsilon_{\rm r}$



Artificial material with negative effective $\varepsilon_{\rm r}$



Charge separation and phase transition controllable with *V, e.g.*, magnetic phase transition controlled with *V*



$$E = E_{H} + \sum_{i} E_{kin,i} + \sum_{i} E_{xc,i} + \sum_{i} E_{corr,i} + \sum_{i} E_{ext,i}$$

• external-parameter (e.g., H) alter E_{corr} , charge separation, R_{SD} sensor applications?

Outlook

- Energies of integrated circuits dive into the quantum regime
- Correlated materials and interfaces in correlated materials change the rules,
 great opportunities
- New devices and circuit design possible:
 new game for FET gate stacks and DS-channels,
 new capacitors, low-C interconnects

Integrating correlated materials enables new approaches to overcome fundamental limits of miniaturization